

## **Altera Device Package Information**

04R-00425-1.0

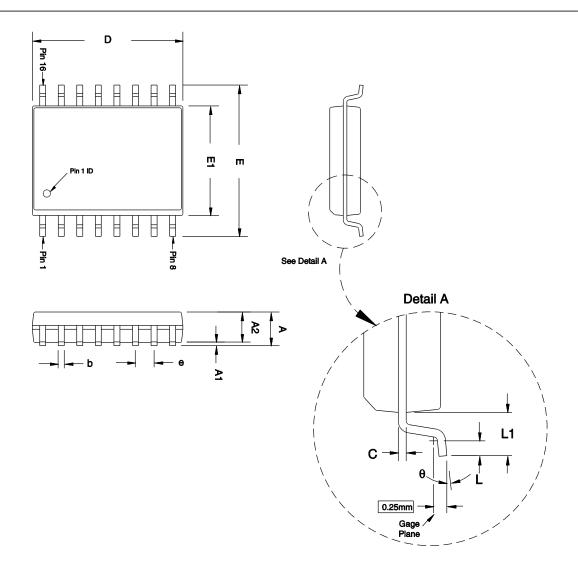
## 16-Pin Small Outline Integrated Circuit Package (SOIC) - Wire Bond

- All dimensions and tolerances conform to ASME Y14.5M 1994.
- Controlling dimension is in millimeters.
- Pin 1 may be indicated by an ID dot, or a special feature, in its proximity on package surface.

Package Information		
Description	Specification	
Ordering Code Reference	S	
Package Acronym	SOIC	
Substrate Material	Copper	
Lead Finish (plating)	Pb-free: NiPdAu (Preplated)	
JEDEC Outline Reference	MS-013 Variation: AA	
Lead Coplanarity	0.1 mm	
Weight	0.5 g (Typ.)	
Moisture Sensitivity Level	Printed on moisture barrier bag	

Symbol	Millimeters			
Зушьог	Min.	Nom.	Max.	
Α	2.35	-	2.65	
A1	0.10	-	0.30	
A2	2.05	-	2.55	
D		10.30 BSC		
E	10.30 BSC 7.50 BSC			
E1				
L	0.40	-	1.27	
L1		1.40 REF		
b	0.31	-	0.51	
С	0.20	-	0.33	
е	1.27 BSC			
θ	0°	-	8°	

## Package Outline



## **Document Revision History**

Table 1 shows the revision history for this document.

Table 1. Document Revision History

Date	Version	Changes
July 2011	1.0	Initial release



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